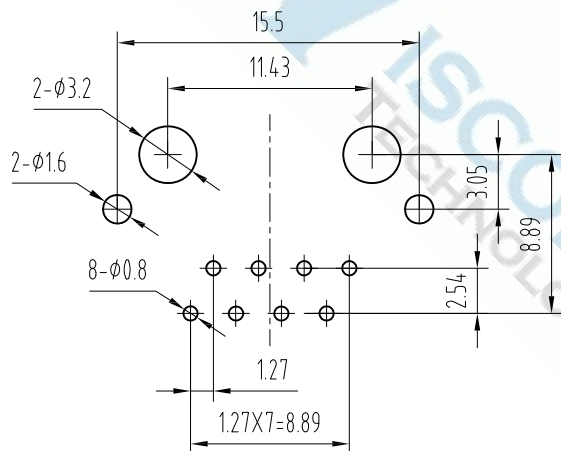


PCB LAYOUT



NOTES:

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :30 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :1000 MEGOHMS MIN @ 500V DC .
- 5.DIELECTRIC STRENGTH :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.HOUSING MATERIAL :LEAD FREE POLYESTER UL94V-0.
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE φ0.46mm ROUND PIN OR T=0.35mm FLAT PIN.
- 3.PLATING :GOLD PLATING OVER NICKEL.
- 4.OPERATING :750 CYCLES MIN.
- 5.SHIELDING :0.20mm THICKNESS COPPER ALLOY WITH NICKEL PLATED.
- 6.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

- 1.Temperature Range : -40℃~+85℃
- 2.Relative Humidity : 90~95% (40±2℃)

MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68, SUBPART F.

DIMENSIONS TOLERANCE METRIC .0=±0.30 .00=±0.20 .000=±0.10 ANG.=±2°	單位<UNITS>	MM	處理<FINISH>	SEE NOTE	審核<CH'K>	Calvin	圖名<NAME>		WISCONN Technology Co., Ltd Tel:02-2742-1798 Fax:02-2742-1898									
	數量<QT'Y>	N/A	繪圖<DRAW>	Johnson	核准<APP'D>	Selena	RJ45 10P8C LOW PROFILE PCB JACK											
	材料<MT'L>	SEE NOTE	設計<DE'N>	Mike	日期<DATE>	OCT.15.2007	料號<PART NUMBER>	WRJ5LP-1008FPBRD	圖號<DRAW NUMBER>	C001	比例<SCALE>	1/1	圖紙<SIZE>	A4	頁次<SHEET>	1	版次<REV.>	A
								圖檔<FILE NAME .DWG>										